

# PC357NT

## Mini-flat Package, General Purpose Photocoupler

### ■ Features

1. Opaque type, mini-flat package  
**PC357NT** (1-channel)
2. Subminiature type  
(The volume is smaller than that of our conventional DIP type by as far as 30 %.)
3. Current transfer ratio  
(CTR: MIN. 50% at  $I_F = 5\text{mA}$ ,  $V_{CE} = 5\text{V}$ )
4. Isolation voltage between input and output  
**PC357NT** •••  $V_{iso} : 3\,750V_{rms}$
5. Recognized by UL ( No. E64380 )

### ■ Applications

1. Hybrid substrates that require high density mounting
2. Programmable controllers

### ■ Package Specifications

Model	Package specifications
<b>PC357NT</b>	Taping reel diameter 178mm ( 750pcs.)

### ■ Absolute Maximum Ratings

( $T_a = 25^\circ\text{C}$ )

Parameter		Symbol	Rating	Unit
Input	Forward current	$I_F$	50	mA
	*1 Peak forward current	$I_{FM}$	1	A
	Reverse voltage	$V_R$	6	V
	Power dissipation	$P$	70	mW
Output	Collector-emitter voltage	$V_{CEO}$	35	V
	Emitter-collector voltage	$V_{ECO}$	6	V
	Collector current	$I_C$	50	mA
	Collector power dissipation	$P_C$	150	mW
	Total power dissipation	$P_{tot}$	170	mW
*2 Isolation voltage		$V_{iso}$	3 750	$V_{rms}$
Operating temperature		$T_{opr}$	- 30 to + 100	$^\circ\text{C}$
Storage temperature		$T_{stg}$	- 40 to + 125	$^\circ\text{C}$
*3 Soldering temperature		$T_{sol}$	260	$^\circ\text{C}$

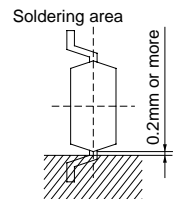
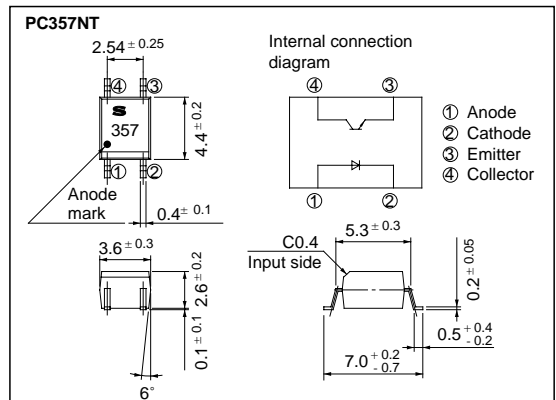
\*1 Pulse width  $\leq 100\mu\text{s}$ , Duty ratio: 0.001

\*2 40 to 60% RH, AC for 1 minute

\*3 For 10 seconds

### ■ Outline Dimensions

(Unit : mm)



## ■ Electro-optical Characteristics

(Ta= 25°C)

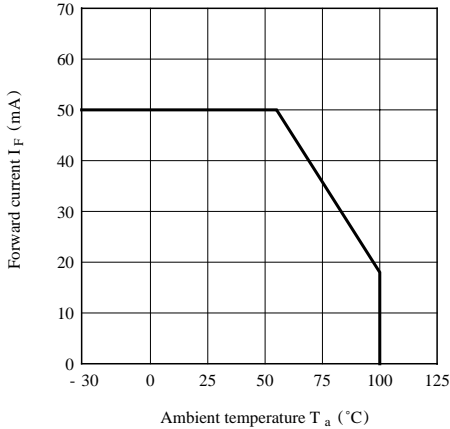
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	$V_F$	$I_F = 20\text{mA}$	-	1.2	1.4	V
	Reverse current	$I_R$	$V_R = 4\text{V}$	-	-	10	$\mu\text{A}$
	Terminal capacitance	$C_t$	$V = 0, f = 1\text{kHz}$	-	30	250	pF
Output	Collector dark current	$I_{CEO}$	$V_{CE} = 20\text{V}, I_F = 0$	-	-	$10^{-7}$	A
	Collector-emitter breakdown voltage	$BV_{CEO}$	$I_C = 0.1\text{mA}, I_F = 0$	35	-	-	V
	Emitter-collector breakdown voltage	$BV_{ECO}$	$I_E = 10\mu\text{A}, I_F = 0$	6	-	-	V
Transfer-characteristics	*4 Current transfer ratio	CTR	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$	50	-	600	%
	Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_F = 20\text{mA}, I_C = 1\text{mA}$	-	-	0.2	V
	Isolation resistance	$R_{ISO}$	DC500V, 40 to 60% RH	$5 \times 10^{10}$	$10^{11}$	-	$\Omega$
	Floating capacitance	$C_f$	$V = 0, f = 1\text{MHz}$	-	0.6	1.0	pF
	Response time	Rise time	$t_r$	$V_{CE} = 2\text{V}, I_C = 2\text{mA}$	-	4	18
Fall time		$t_f$	$R_L = 100\Omega$	-	3	18	$\mu\text{s}$

\*4 Classification table of current transfer ratio is shown below.

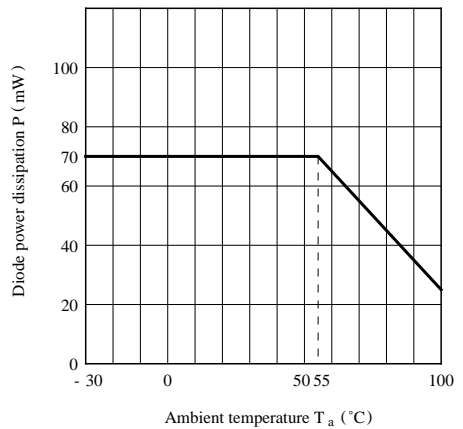
## ■ Current Transfer Ratio (CTR) Line-ups

Model No.	Rank mark	CTR (%)
PC357N1T	A	80 to 160
PC357N2T	B	130 to 260
PC357N3T	C	200 to 400
PC357N4T	D	300 to 600
PC357N5T	A or B	80 to 260
PC357N6T	B or C	130 to 400
PC357N7T	C or D	200 to 600
PC357N8T	A, B or C	80 to 400
PC357N9T	B, C or D	130 to 600
PC357N0T	A, B, C or D	80 to 600
PC357NT	A, B, C, D or No mark	50 to 600

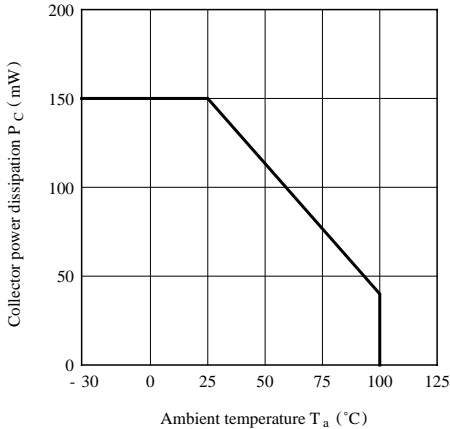
**Fig. 1 Forward Current vs. Ambient Temperature**



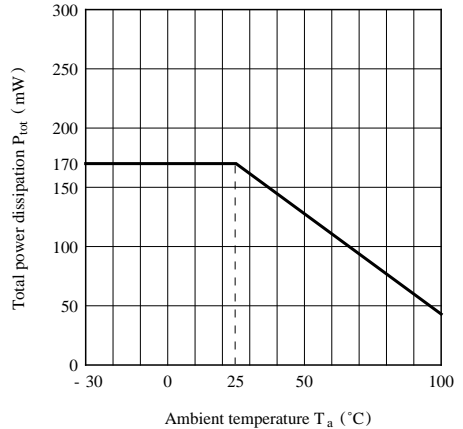
**Fig. 2 Diode Power Dissipation vs. Ambient Temperature**



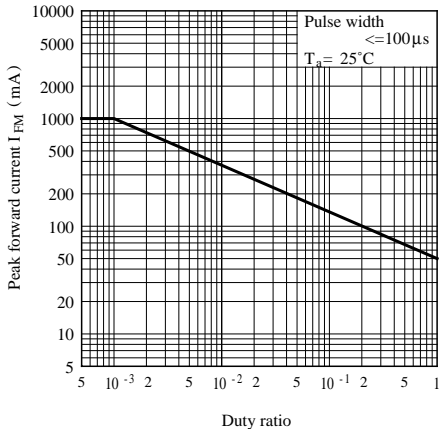
**Fig. 3 Collector Power Dissipation vs. Ambient Temperature**



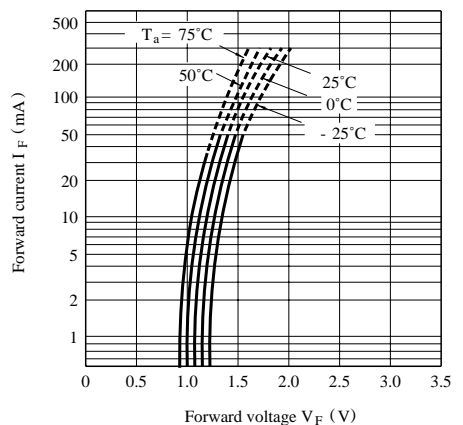
**Fig. 4 Total Power Dissipation vs. Ambient Temperature**



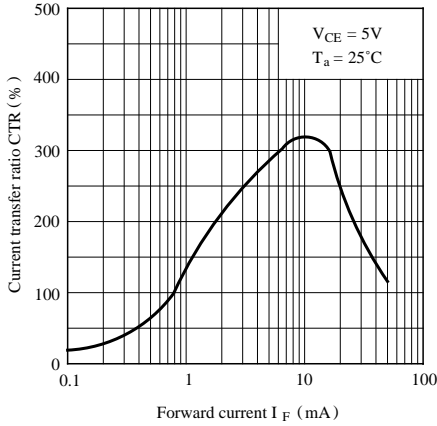
**Fig. 5 Peak Forward Current vs. Duty Ratio**



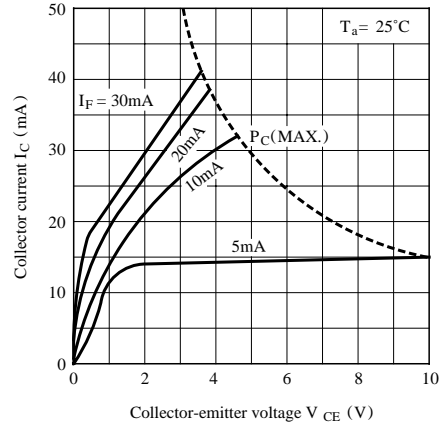
**Fig. 6 Forward Current vs. Forward Voltage**



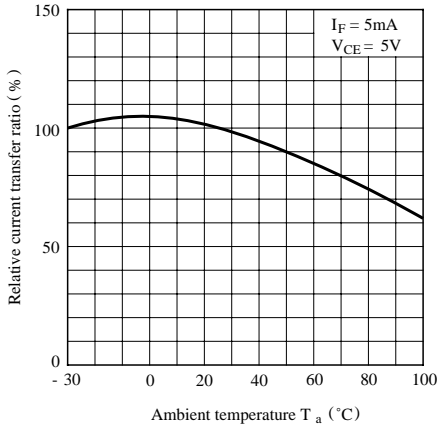
**Fig. 7 Current Transfer Ratio vs. Forward Current**



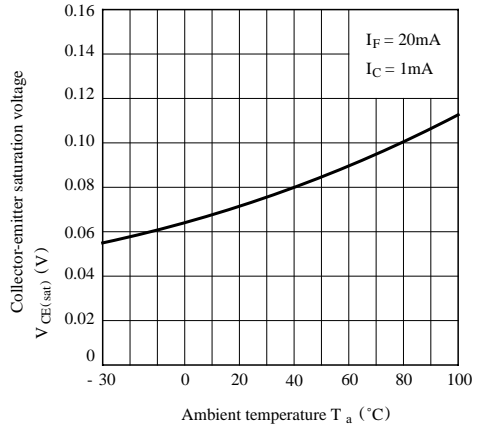
**Fig. 8 Collector Current vs. Collector-emitter Voltage**



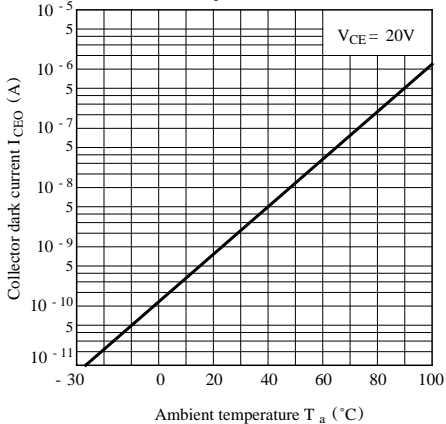
**Fig. 9 Relative Current Transfer Ratio vs. Ambient Temperature**



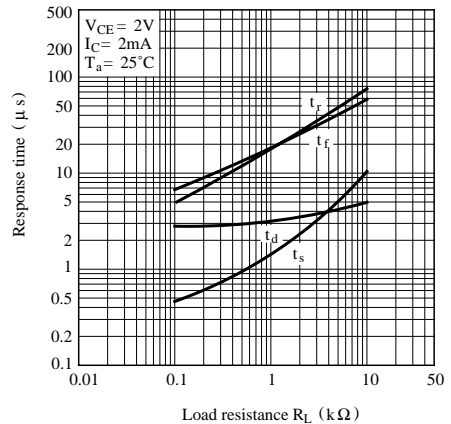
**Fig.10 Collector-emitter Saturation Voltage vs. Ambient Temperature**



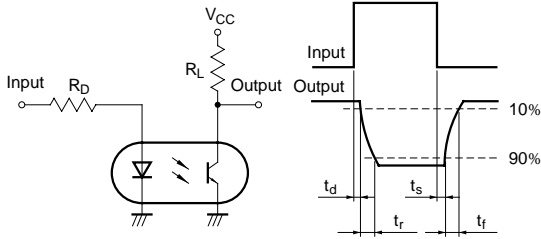
**Fig.11 Collector Dark Current vs. Ambient Temperature**



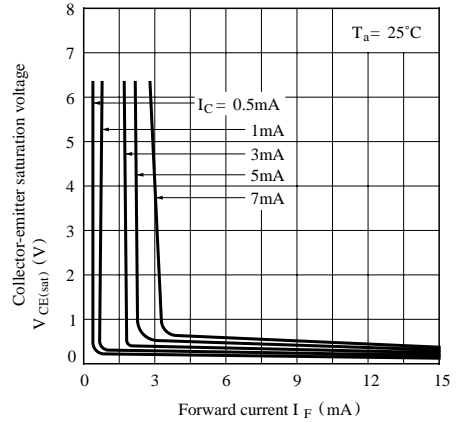
**Fig.12 Response Time vs. Load Resistance**



**Test Circuit for Response Time**

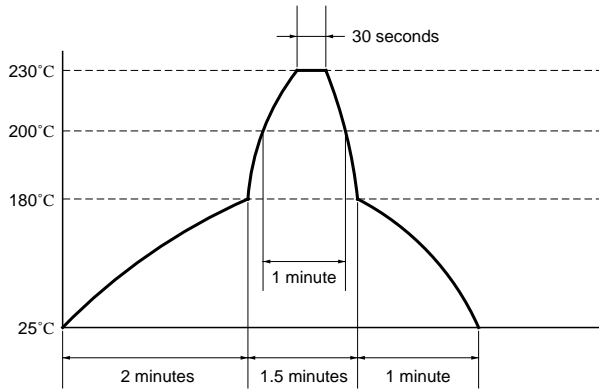


**Fig.13 Collector-emitter Saturation Voltage vs. Forward Current**



**Temperature Profile of Soldering Reflow**

(1) One time soldering reflow is recommended within the condition of temperature and time profile shown below.



(2) When using another soldering method such as infrared ray lamp, the temperature may rise partially in the mold of the device.

Keep the temperature on the package of the device within the condition of above (1).

(3) As for other general cautions, refer to the chapter "Precautions for Use"

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